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		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
APPLICATION NO.	FILING DATE	Jiunn-Ren Hwang	NAUP0292USA	3189
09/851,580	05/10/2001	Jiunn-Ken riwang		
27765 7	590 12/18/2002	TERNATIONAL PATENT OFFICE	EXAMINER	
P ∩ ROX 506			RUGGLES, JOHN S	
MERRIFIELD	, VA 22116		ART UNIT	PAPER NUMBER
			1756 DATE MAILED: 12/18/2002	. 4

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

Applicant(s) Application No. HWANG ET AL. 09/851,580 Art Unit Examiner 1756 John Ruggles

The MAILING DATE of this communication appears on the cover sheet with the correspondence address –

#### Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM

THE MAILING DATE OF THIS COMMUNICATION

- Extensions of time may be available under the provisions of 37 CFR 1.135(a). In no event, however, may a reply be timely filed
- after SIX. (c) MUM INS from the making date of this communication.

  If the period for reply specified above is less than thirty (30) days, will be considered timely,

  If the period for reply specified above, its maximum will be provided by the provided strain of the statutory minimum of thirty (30) days will be considered timely,

  If NO period for reply is specified above, the maximum will by statute, cause the application to become ARAMOVARC (31 QL SC § 135).

  Failure to reply within the set or extended period for only and the statute of t

	Failure to reply within the Set of water than three months after the mailing date of this communication, see that the control of the search of the sear							
Sta			1 00 March 2002					
	1)⊠	Responsive to communication(s) f	filed on 22 March 2002.	final				
2	2a)	This action is FINAL.	2b)⊠ This action is non	termal matters, prosecution as to the ments is				
	<ol> <li>Since this application is in condition for allowance except for formal matters, closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.</li> </ol>							
Disposition of Claims								
	4)🖾	Claim(s) 1-6 is/are pending in the	application.	deration				
	4a) Of the above claim(s) is/are withdrawn from consideration.							
	5) Claim(s) is/are allowed.							
	6)⊠ Claim(s) <u>1-6</u> is/are rejected.							
1	is/are objected to.							
	8) Claim(s) are subject to restriction and/or election requirement.							
Application Papers								
	10) ☐ The drawing(s) filed on 10 May 2001 Israel. a) Green state of the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
The record drawing correction filed on is: a) approved b) also proved by								
If approved, corrected drawings are required in reply to this simple and the simple si								
1	12) The oath or declaration is objected to by the Examiner.							
Priority under 35 U.S.C. §§ 119 and 120  13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).								
1	13)[	Acknowledgment is made of a cl	laim for foreign priority und	er 35 U.S.C. 9 115(a) (5) 51 (7)				
	ے,د.	. The LIT Come * c) None	of:					
	•			received.				
	2. Certified copies of the priority documents have been received in this National Stage 3. Copies of the certified copies of the priority documents have been received in this National Stage							
	application from the International Bureau (FO) Note: The Control of the Certified copies not received.  * See the attached detailed Office action for a list of the certified copies not received.							
-	at a claim for domestic priority under 35 8.8.8.3							
	14) ☐ Acknowledgment is made of a claim to downward and the second at the second							
- 1	Attachment(s)  4) Interview Summary (PTO-413) Paper No(s)							
	1) 🛛 🎙	Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Rei	view (PTO-948) 449) Paper No(s) ·	Interview Summary (F10-413)   Span       Notice of Informal Patent Application (PT0-152)     Other:				

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## DETAILED ACTION

### Specification

Applicant is reminded of the proper language and format for an abstract of the disclosure.

The abstract should be in narrative form and generally limited to a single paragraph on a separate sheet within the range of 50 to 150 words. It is important that the abstract not exceed 150 words in length since the space provided for the abstract on the computer tape used by the printer is limited. The form and legal phraseology often used in patent claims, such as "means" and "said," should be avoided. The abstract should describe the disclosure sufficiently to assist readers in deciding whether there is a need for consulting the full patent text for details.

The language should be clear and concise and should not repeat information given in the title. It should avoid using phrases which can be implied, such as, "The disclosure concerns," "The disclosure defined by this invention," "The disclosure describes." etc.

The abstract of the disclosure is objected to because it has more than 150 words. Correction is required. See MPEP § 608.01(b).

## Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United

Claim 3 is rejected under 35 U.S.C. 102(b) as being anticipated by Ueno

(Japanese Patent Publication 01-107527). Ueno teaches a method of preventing two-

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dimensional (optical proximity) effects caused by light diffraction during a photolithography process to form (define) a rectangular (array) pattern. A negative photosensitive resin (photoresist) is formed on a semiconductor substrate. The photoresist is exposed through a first linear mask pattern, 100 (having parallel lines, 101), shown in Figure 1(a). Then the photoresist is exposed through a second linear mask pattern, 200 (having parallel lines, 201), shown in Figure 1(b) and positioned in perpendicular relation to the first exposure pattern to form an array of rectangular unexposed photoresist regions, 400, shown in Figure 2(a).

### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-2 and 4-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ueno as applied to claim 3 above, and further in view of Adair (US Patent 6,184,151).

Ueno is discussed above, but does not specify subsequent etching of the substrate using the remaining photoresist pattern as an etching mask and does not specify the formation of storage nodes for a dynamic random access memory (DRAM).

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Ueno also does not specify that the optical proximity effects to be avoided were corner rounding and pattern shortening.

Adair states that in order to scale down DRAM devices while maintaining sufficient capacitance, corner rounding and shortening effects should be avoided when forming the storage nodes (capacitors) in column 1, at lines 46-53. Adair also teaches plural perpendicular exposures (using masks having parallel linear patterns) of one or more photoresist layers to obtain sharp-edged corners (without significant corner rounding or image shortening) in the resulting photoresist image, followed by etching of an underlying substrate through the remaining photoresist pattern as an etching mask in column 6, at lines 6-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the Ueno double exposure method to form a rectangular array of unexposed photoresist portions with the DRAM storage node formation by subsequent etching taught by Adair. The expected result of this combination would be to avoid corner rounding and image shortening during DRAM storage node formation.

#### Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

The following patents and publications are cited to further show the state of the art with respect to avoiding photolithographic optical proximity effects by multiple exposures, especially as related to manufacture of DRAM devices:

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US Patents 5,849,437, 5,885,749, 6,090,527, 6,168,904, 6,228,564, 6,238,850, and 6,451,508. US Patent Application Publications 2002/0059557 and 2002/0068243.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to John Ruggles whose telephone number is 703-305-7035. The examiner can normally be reached on Monday-Thursday and alternate Fridays.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Mark Huff can be reached on 703-308-2464. The fax phone numbers for the organization where this application or proceeding is assigned are 703-872-9310 for regular communications and 703-872-9311 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-

0661.

John-Ruggles Examiner

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MARK F. HUFF SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 1700